



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-14
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMS Material Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
74LCX07YMTR	IDK7*E00716Y	A	BO2A	2016-06-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	130.00	mg	Each	ECOPACK® 3
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: SO 14 .15 TO JEDEC MS-012			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDK7*E0076Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	0.981	mg	supplier	die	Silicon (Si)	7440-21-3		0.959	mg	977574	7377
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	5097	38
				supplier	metallization	Titanium (Ti)	7440-32-6		0.002	mg	2039	15
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	1019	8
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	2039	15
				supplier	Passivation	Silicon Oxide	7631-86-9		0.012	mg	12232	92
Leadframe	Copper & its alloys	58.828	mg	supplier	alloy	Copper (Cu)	7440-50-8		57.180	mg	971986	439846
				supplier	alloy	Iron (Fe)	7439-89-6		1.345	mg	22863	10346
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.081	mg	1377	623
				supplier	alloy	Zinc (Zn)	7440-66-6		0.070	mg	1190	538
				supplier	metallization	Nickel (Ni)	7440-02-0		0.139	mg	2363	1069
				supplier	metallization	Palladium (Pd)	7440-05-3		0.005	mg	85	38
				supplier	metallization	Gold (Au)	7440-57-5		0.004	mg	68	31
				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	68	31
Die attach	Other inorganic materials	0.407	mg	supplier	glue or tape (choose)	Silver (Ag)	7440-22-4		0.371	mg	911548	2854
				supplier	glue or tape	acrylate	Proprietary		0.020	mg	49140	154
				supplier	glue or tape	Methacrylate	Proprietary		0.016	mg	39312	123
Bonding wire	Other inorganic materials	0.145	mg	supplier	wire	Copper (Cu)	7440-50-8		0.145	mg	1000000	1115
encapsulation	Other inorganic materials	69.639	mg	supplier	mold compound	Epoxy Resin	25068-38-6		5.223	mg	75001	40177
				supplier	mold compound	Phenol Resin	29690-82-2		3.482	mg	50001	26785
				supplier	mold compound	Silica, vitreous	60676-86-0		60.307	mg	865995	463900
				supplier	mold compound	Carbon black	1333-86-4		0.349	mg	5012	2685
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.278	mg	3992	2138